

- Contributes to energy savings by reducing power loss, while also reducing inverter loss by 10% and chip temperature by 11°C (Comparison with the 6th Generation V Series EP3 Package (75 A), at $f_{\rm c}$ = 8 kHz)
- Achieves equipment miniaturization
 Footprint size can be reduced by 36% by replacing the previous
 6th Generation V Series EP3 (75 A) with the new 7th Generation X Series
 EP2 (75 A) (See *1)
- Contributes to improved equipment reliability Achieves guaranteed continuous operation at $T_{\rm vj(op)}$ = 175°C





Package (typical example)

Application example: General motor drives UPS, PCS, others





1. Low loss

The module has been optimized by thinning the thickness and miniaturizing the structure of the IGBT chip and diode chip that makes up the module.

This reduces power losses during inverter operation compared with previous products (our 6th generation V series).

Reduces inverter loss by 10% and chip temperature by 11 $^{\circ}$ C (Comparison with the 6th Generation V Series EP3 Package (75 A), at $f_{\rm c}$ = 8 kHz)

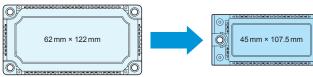
120.0 ■ P₋₋ : Reverse recovery loss Inverter Power Losses [W] Temperatu 100.0 100 ■P_f : FWD conduction loss Junction Ter., 7., [deg.C] 80.0 80 ■Pon : Turn-on loss ■P_{off}: Turn-off loss 60 60.0 ■P_{sat}: IGBT conduction loss 40 40.0 $\triangle T_{vj}$: Junction temperature GBT 20.0 $\begin{array}{c} \text{generation generation} \\ \text{(EP3)} \\ f_{\text{c}}\text{=-4 kHz} \end{array} \\ \begin{array}{c} \text{(EP2)} \\ \text{(EP3)} \\ \text{(EP3)} \end{array} \\ \begin{array}{c} \text{(EP3)} \\ \text{(EP2)} \\ \text{(EP3)} \end{array}$ V_{DC} =600 V, I_{O} =35 Arms, I_{O} =50 Hz Power factor = +0.9, modulation factor = 1.0. Reverse recovery dv/dt = 10 kV/us

2. Miniaturization

The application of the newly developed insulating board has improved the heat dissipation of the module. A smaller footprint of about 36% has been achieved by reducing power loss and suppressing heat generation compared with the previous product.

Application example)

36% reduction



EP3 75 A (6th Generation V Series)

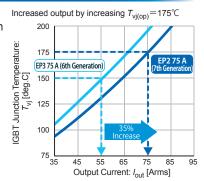
EP2 75 A (7th Generation X Series)

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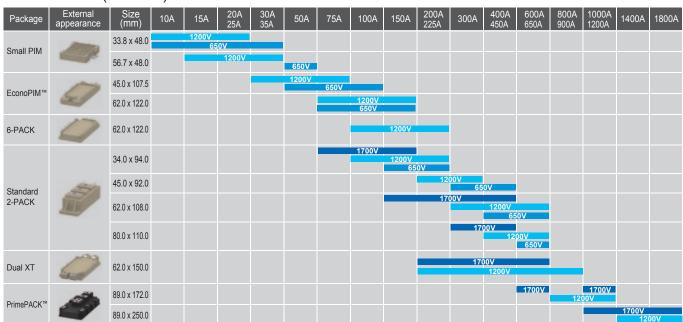
3. High-temperature operation

Achieves continuous operation at 175 °C through chip optimization and improved package reliability and heat resistance.

- Up to 35% more output than the previous generation
- · Δ*T*_{vj} power cycle capability improvement (twice as high as before)



Product series (tentative) 1700 V /1200 V /650 V



Power Integrated Modules are products that integrate multiple circuits in one module. $EconoPIM^{\intercal M} \ and \ PrimePACK^{\intercal M} \ are \ registered \ trademarks \ of \ Infineon \ Technologies \ AG$

▲ Safety Precautions

- *Before using this product, read the "Instruction Manual" and "Specifications" carefully, and consult with the retailer from which you purchased this product as necessary to use this product correctly.
- *The product must be handled by a technician with the appropriate skills.

Fuji Electric Co., Ltd.

URL http://www.fujielectric.com/products/semiconductor/ Gate City Ohsaki, East Tower, 1-11-2, Osaki, Shinagawa-ku, Tokyo 141-0032, Japan Tel:+81-3-5435-7156

Suites 1911-13, 19/F., Tower 6, The Gateway, Harbour City, Tsim Sha Tsui, Kowloon, Hong Kong

- Fuji Electric Hong Kong Co., Ltd.
 Fuji Electric Taiwan Co., Ltd.
- Fuji Electric Taiwan Co., Ltd.
- Fuji Electric Asia Pacific Pte. Ltd.
 Fuji Electric Corp. of America
- Fuji Electric Europe GmbH
- 10F. No.168, Song Jiang Road, Taipei, Taiwan
- 151 Lorong Chuan, #2-01A, New Tech Park, SINGAPORE 556741 50 Northfield Avenue Edison, NJ 08837, USA
- Goethering 58, 63067 Offenbach, am Main, F.R. GERMANY

Tel: +886-2-2515-1850 Tel: +65-6533-0014 Tel: +1-732-560-9410 Tel: +49-69-6690290

Tel: +852-2664-8699

